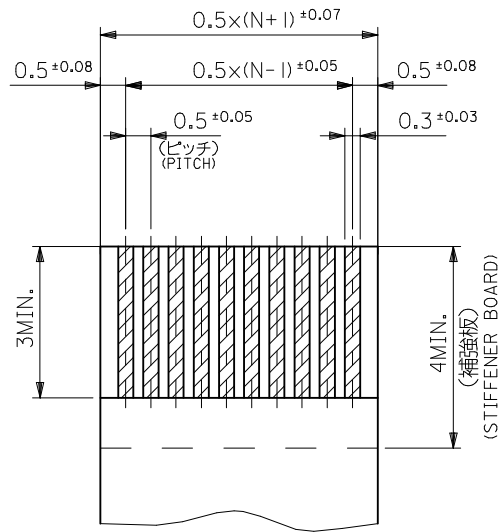
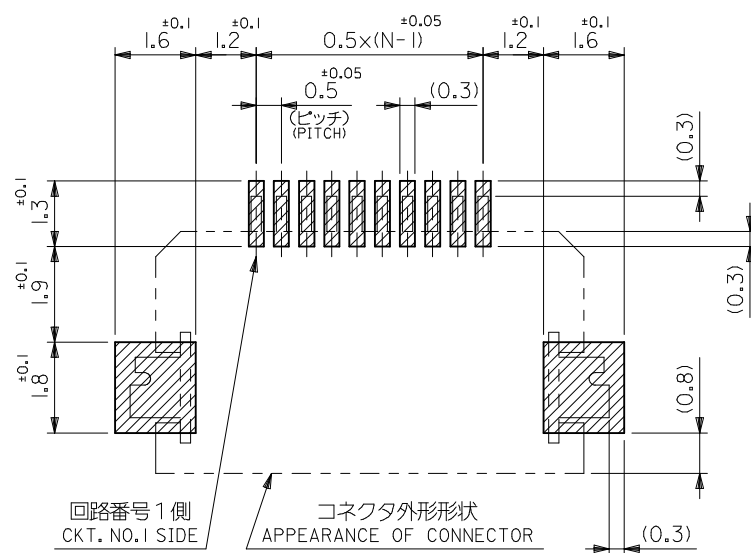


適合FPC推奨寸法
APPLICABLE FPC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS : 0.3±0.03)

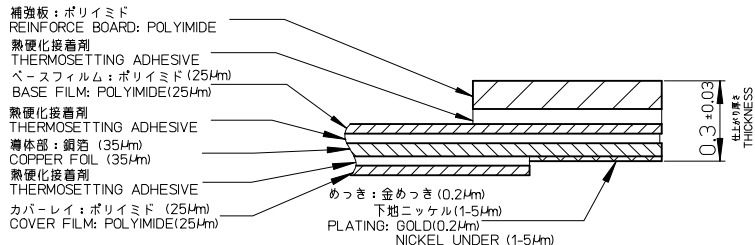


適合FFC推奨寸法
APPLICABLE FFC
RECOMMENDED DIMENSION
(仕上がり厚さ: 0.3±0.03)
(THICKNESS : 0.3±0.03)



推奨基板レイアウト
RECOMMENDED P.C.BOARD
PATTERN DIMENSION
(マウント面)
(MOUNTING SIDE)

マスク厚 : 100µm
マスク開口率: 100%
SCREEN THICKNESS : 100MICROMETER
SCREEN OPEN RATIO : 100%



FPC構成推奨仕様
STRUCTURE OF FPC

FPC/FFCについて ABOUT FPC/FFC
打ち抜き方向は導体側から補強板側を推奨します。
導体部については数層銅35µmまたは50µmを推奨します。
RECOMMENDED PUNCHING DIRECTION: FROM CONDUCTOR SIDE TO STIFFENER SIDE
RECOMMENDED CONDUCTOR SPEC: SOFT COPPER FOIL
RECOMMENDED CONDUCTOR THICKNESS: 35 MICROMETER OR 50 MICROMETER

FPCについてABOUT FPC
補強フィルム材質はポリイミドを推奨します。ベースフィルムは25µmを推奨します。
接着剤は熱硬化接着剤を推奨します。
尚、接着剤の接点部への付着は導通不良の原因になりますので、染み出しが無い様、お願い致します。
RECOMMENDED STIFFENER MATERIAL: POLYIMIDE
RECOMMENDED BASE FILM THICKNESS: 25 MICROMETER
RECOMMENDED ADHESIVE: THERMOSETTING ADHESIVE
NOTE: PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE ON ADHEREND BECAUSE THERE IS A POSSIBILITY THAT THE EXTRA ADHESIVE CAUSES THE DEFECT IN ELECTRICAL CONTINUITY.

REVISED EC NO.: J2013-1133 DRWN: SANUMA 2013/04/11 CHKD: TAKAHASHI 2013/04/11 APPR: KMORIKAWA 2013/04/16 A	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY NKONDO	DATE 2012/09/18	TITLE 0.5MM FFC/FPC CONN NON-ZIF HSG ASSY (LOWER CONTACT)			
		10 OVER 30 UNDER	±0.25	CHECKED BY KTAKAHASHI	DATE 2012/09/18	molex			
		30 OVER	±0.3	APPROVED BY KMORIKAWA	DATE 2013/03/15				
ANGULAR ±3 °		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO. SEE CHART		DOCUMENT NO. SD-52976-016		SHEET NO. 2 OF 2	
SIZE A3 THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									

52976-**-22 MODEL NO.